Global 3D IC and 2.5D IC Packaging Market Growth 2025-2031

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Abstracts

The global 3D IC and 2.5D IC Packaging market size is predicted to grow from US$ 146190 million in 2025 to US$ 347980 million in 2031; it is expected to grow at a CAGR of 15.6% from 2025 to 2031.

The impact of the latest U.S. tariff measures and the corresponding policy responses from countries worldwide on market competitiveness, regional economic performance, and supply chain configurations will be comprehensively evaluated in this report.

Following a strong growth of 26.2 percent in the year 2021, WSTS revised it down to a single digit growth for the worldwide semiconductor market in 2022 with a total size of US$580 billion, up 4.4 percent. WSTS lowered growth estimation as inflation rises and end markets seeing weaker demand, especially those exposed to consumer spending. While some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.8 percent, Sensors with 16.3 percent, and Logic with 14.5 percent growth. Memory declined with 12.6 percent year over year. In 2022, all geographical regions showed double-digit growth except Asia Pacific. The largest region, Asia Pacific, declined 2.0 percent. Sales in the Americas were US$142.1 billion, up 17.0% year-on-year, sales in Europe were US$53.8 billion, up 12.6% year-on-year, and sales in Japan were US$48.1 billion, up 10.0% year-on-year. However, sales in the largest Asia-Pacific region were US$336.2 billion, down 2.0% year-on-year.

LP Information, Inc. (LPI) ' newest research report, the “3D IC and 2.5D IC Packaging Industry Forecast” looks at past sales and reviews total world 3D IC and 2.5D IC Packaging sales in 2024, providing a comprehensive analysis by region and market sector of projected 3D IC and 2.5D IC Packaging sales for 2025 through 2031. With 3D IC and 2.5D IC Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US$ millions of the world 3D IC and 2.5D IC Packaging industry.

This Insight Report provides a comprehensive analysis of the global 3D IC and 2.5D IC Packaging landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on 3D IC and 2.5D IC Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global 3D IC and 2.5D IC Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for 3D IC and 2.5D IC Packaging and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global 3D IC and 2.5D IC Packaging.

This report presents a comprehensive overview, market shares, and growth opportunities of 3D IC and 2.5D IC Packaging market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

3D Wafer-level Chip-scale Packaging

3D TSV

2.5D

Segmentation by Application:

Logic

Imaging & Optoelectronics

Memory

- MEMS/Sensors
- LED
- Power

This report also splits the market by region:

- Americas
  - United States
  - Canada
  - Mexico
  - Brazil
- APAC
  - China
  - Japan
  - Korea
  - Southeast Asia
  - India
  - Australia
- Europe
  - Germany
  - France

  - UK
  - Italy
  - Russia
- Middle East & Africa
  - Egypt
  - South Africa
  - Israel
  - Turkey
  - GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

- Taiwan Semiconductor
- Samsung Electronics
- Toshiba Corp
- Advanced Semiconductor Engineering
- Amkor Technology

Key Questions Addressed in this Report

What is the 10-year outlook for the global 3D IC and 2.5D IC Packaging market?

What factors are driving 3D IC and 2.5D IC Packaging market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?
How do 3D IC and 2.5D IC Packaging market opportunities vary by end market size?
How does 3D IC and 2.5D IC Packaging break out by Type, by Application?

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